

Abstract

SILVER-GOLD-PALLADIUM ALLOY BUMPING WIRE

A silver-gold-palladium bumping wire for a semiconductor device, which enables to stabilize a fluctuation in tail length by shortening a tail length of a molten ball. In a vertically pull-cut silver-gold-palladium alloy bumping wire, a silver-gold-palladium alloy includes 1 to 9 mass% of gold (Au) and 0.5 to 5 mass% of palladium (Pd) with the balance being silver (Ag) having purity of 99.995 mass% or more (excluding the above-described contained elements), and Vickers hardness of the bumping wire before molten ball formation is 80 to 100 Hv.

Fig. 1